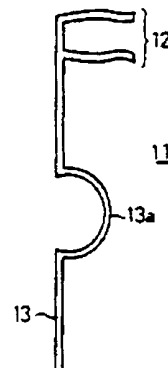
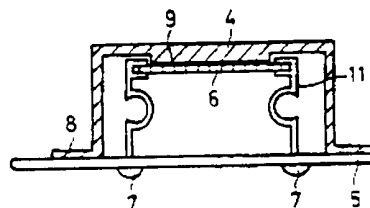

TITLE : CLIP LEAD



CONSTITUTION: A bent section 13a functions as a stress cushioning section shaped to a lead section 12. A hybrid integrated circuit substrate 6 is mounted by using the clip leads 11, thus cushioning stress by thermal stress brought by heat applied to sections having different expansion coefficients and other various stress by the bent sections 13a in the clip leads 11. Accordingly, clips sections 12 for the clip leads 11 and the hybrid integrated circuit substrate 6 are not peeled, and a printed substrate 5 is not damaged by the upward pulling of the clip leads 11.

COPYRIGHT: (C) JPO